Poster Presentaion | Nov. 10, 2022 (Thu.) 13:10~14:00 P.M. Lobby (3F)

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P-003	Study of S-Parameter Characteristics on Substrate Material in Trench Capacitor Structure for IPD	Seon-Kwon Kim, Hui-Geun Kang, Dong-Wook Kim, Jun-Seong Ji, Jung-Rae Park, Gu-Sung Kim	Kangnam University	kr
P-004	5G Filtering Power Divider using Substrate Integrated Waveguide Resonator with Multi-slots	Seunggoo Nam†, Sehoon Choi	Korea Electronics Technology Institute (KETI)	kr
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P-007	Stacked Through-hole Silicon Capacitors for High Density Applications	Su-Geun Kim, Seong-Jun Im, Hyun-Je Chang, Jong-Min Yook	Korea Electronics Technology Institute (KETI)	kr
P-008	Control of Size and Morphology of Dendrite-Shape Cu Particles and Improvement of Pressure-Assisted Sinter-Bondability	Sang-Hoon Jung, Jong-Hyun Lee	Seoul National University of Science and Technology	kr
P-009	Effects of Surface Treatment with Carboxylic Acids on Sinter Bonding Using Bimodal Cu Particles	Wan-Geun Lee, Jong-Hyun Lee	Seoul National University of Science and Technology	kr
P-010	Assessment of AF4 Parylene Adhesion on Si and SiO_2 Substrates by Means of Pull-off Energy	Taulant Sinani, Dmytro Solonenko, Goran Miskovic	Silicon Austria Labs (SAL)	at
P-011	Mechanical Reliability Improvement of Cu-Mn Interconnect for Flexible Electronics Through Self-forming Process	Jae-Myeong Shin, Seongi Lee, Won-Jun Lee, Young-Chang Joo, Byoung-Joon Kim	Tech University of Korea, Seoul National University, Sejong University	kr
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P-013	Cu/Oxide Hybrid Bonding Analysis by Finite Element Modeling	Gwang-Sik Oh, Cha-Hee Kim, Won-Jun Lee, Jiho Kang, Jung Hwan Park, Young Su Yun, Sarah Eunkyung Kim	Seoul National University of Science and Technology, Sejong University	kr
P-014	In-situ Temperature-dependent Sheet Resistance of Cu Films in Oxygen Ambient for Wafer-Level 3D IC Integrations	Kyeong-Keun Choi, Sung-Kyu Kim	Pohang University of Science and Technology (POSTECH)	kr
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P-016	Comparative Study on the Microstructures and Mechanical Reliability of the Sn-58Bi-xPt Solder Joints Reacted with ENIG and ENEPIG Surface Finishes	Jun-Hyuk Bae, Yoonchul Sohn	Chosun University	kr
P-018	Demonstration of Ferrite core Embedded Solenoid Inductor Using LASER Modification Chemical Etching on Glass Substrate	Insub Han, Jongmin Yook, Jein Yu	Korea Electronics Technology Institute (KETI)	kr
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